

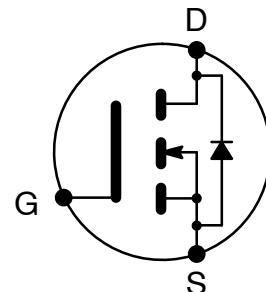


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**NTE2900
MOSFET
N-Ch, Enhancement Mode
High Speed Switch
TO220 Type Package**

Features:

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Parallelizing
- Simple Drive Requirements



Absolute Maximum Ratings:

Continuous Drain Current ($V_{GS} = 10V$), I_D

$T_C = +25^\circ C$	14A
$T_C = +100^\circ C$	8.5A

Pulsed Drain Current (Note 1), I_{DM}

56A

Power Dissipation ($T_C = +25^\circ C$), P_D

125W

Derate Linearly Above $25^\circ C$

1.0W/ $^\circ C$

Gate-to-Source Voltage, V_{GS}

± 20

Single Pulse Avalanche Energy (Note 2), E_{AS}

550mJ

Avalanche Current (Note 1), I_{AR}

14A

Repetitive Avalanche Energy (Note 1), E_{AR}

13mJ

Peak Diode Recovery dv/dt (Note 3), dv/dt

4.8V/ns

Operating Junction Temperature Range, T_J

-55° to +175°C

Storage Temperature Range, T_{stg}

-55° to +175°C

Lead Temperature (During Soldering, 1.6mm from case for 10sec), T_L

+300°C

Mounting Torque (6-32 or M3 Screw)

10 lbf•in (1.1N•m)

Thermal Resistance, Junction-to-Case, R_{thJC}

1.0°C/W

Thermal Resistance, Junction-to-Ambient, R_{thJA}

62°C/W

Typical Thermal Resistance, Case-to-Sink (Flat, Greased Surface), R_{thCS}

0.5°C/W

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 2. $V_{DD} = 25V$, starting $T_J = +25^\circ C$, $L = 4.5mH$, $R_G = 25\Omega$, $I_{AS} = 14A$

Note 3. $I_{SD} \leq 14A$, $di/dt \leq 150A/\mu s$, $V_{DD} \leq 250V$, $T_J \leq +175^\circ C$

Note 4. Pulses Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

Electrical Characteristics: ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	250	—	—	V
Breakdown Voltage Temp. Coefficient	$\frac{\Delta V_{(\text{BR})\text{DSS}}}{\Delta T_J}$	Reference to $+25^\circ\text{C}$, $I_D = 1\text{mA}$	—	0.34	—	$\text{V}/^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 8.4\text{A}$, Note 4	—	—	0.28	Ω
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	—	4.0	V
Forward Transconductance	g_{fs}	$V_{\text{DS}} = 50\text{V}, I_D = 8.4\text{A}$, Note 4	6.7	—	—	mhos
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}} = 250\text{V}, V_{\text{GS}} = 0\text{V}$	—	—	25	μA
		$V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}, T_J = +125^\circ\text{C}$	—	—	250	μA
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{GS}} = 20\text{V}$	—	—	100	nA
Gate-to-Source Reverse Leakage	I_{GSS}	$V_{\text{GS}} = -20\text{V}$	—	—	-100	nA
Total Gate Charge	Q_g	$I_D = 7.9\text{A}, V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 10\text{V}$, Note 4	—	—	68	nC
Gate-to-Source Charge	Q_{gs}		—	—	11	nC
Gate-to-Drain ("Miller") Charge	Q_{gd}		—	—	35	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 125\text{V}, I_D = 7.9\text{A}, R_G = 9.1\Omega, R_D = 8.7\Omega$, Note 4	—	11	—	ns
Rise Time	t_r		—	24	—	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		—	53	—	ns
Fall Time	t_f		—	49	—	ns
Internal Drain Inductance	L_D	Between lead, .250in. (6.0) mm from package and center of die contact	—	4.5	—	nH
Internal Source Inductance	L_S		—	7.5	—	nH
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	—	1300	—	pF
Output Capacitance	C_{oss}		—	330	—	pF
Reverse Transfer Capacitance	C_{rss}		—	85	—	pF

Source-Drain Ratings and Characteristics:

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	I_S		—	—	14	A
Pulsed Source Current (Body Diode)	I_{SM}	Note 1	—	—	56	A
Diode Forward Voltage	V_{SD}	$T_J = +25^\circ\text{C}, I_S = 14\text{A}, V_{\text{GS}} = 0\text{V}$, Note 4	—	—	1.8	V
Reverse Recovery Time	t_{rr}	$T_J = +25^\circ\text{C}, I_F = 7.9\text{A}$, $dI/dt = 100\text{A}/\mu\text{s}$, Note 4	—	250	500	ns
Reverse Recovery Charge	Q_{rr}		—	2.3	4.6	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Note 1. Repetitive rating; pulse width limited by maximum junction temperature.

Note 4. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

